



CERTIFICATE

This is to certify that

STATS ChipPAC Taiwan Semiconductor Corporation

No. 176-5, Lu Liao Ken, 6 Ling, Hua Lung Chun
Chiung Lin, Hsin Chu Hsien, Taiwan, R.O.C. 307

has implemented and maintains a **Quality Management System**.

Scope:

The manufacturing of wafer bumping and the production of integrated circuit device trimming.

An audit, conducted and documented in a report, has verified that this quality management system fulfills the requirements of the following ISO Technical Specification:

ISO/TS 16949 : 2009

(without product design)

Original certification date	2010-05-18
Certification decision	2010-05-18
This certificate is valid until	2013-05-17
Certificate Registration No.	20002839 TS09
IATF No.	0103049
Main Certificate Registration No.	20002839 TS09
Buffalo Grove, IL, USA	2011-06-19



2-IAO-QMC-01001



Ganesh Rao
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